



MSM64V256CB - 015/020
Issue 1.0 Sept 2001

256K x 64 Static RAM

Description

The MSM64V256CB is a 16MBit Fast 3.3V SRAM available in a multichip 192 ball BGA(Ball Grid Array) package. The device can be organised as 256Kx64, 512Kx32 and 1Mx16. Access times of 15 and 20ns are available at Commercial or Industrial temperature grades.

The multichip BGA provides an ultra high density memory packaging solution which occupies less board space than the equivalent traditional off-the-shelf packages.

Features

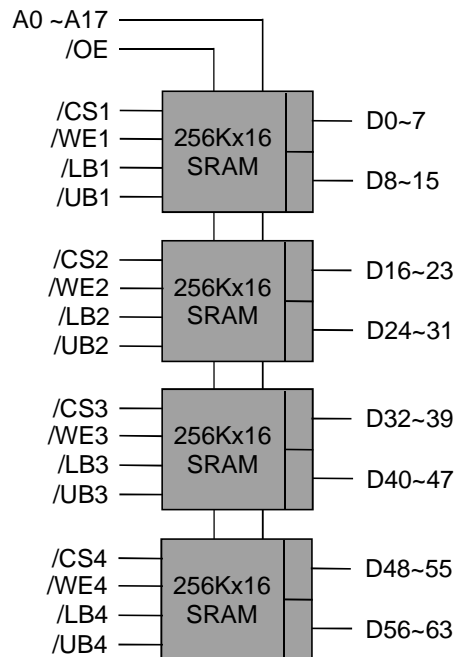
- 16Mbit High Speed Asynchronous SRAM.
- 3.3V \pm 10%.
- Flexible architecture which allows device to be used as 256Kx64, 512Kx32 and 1Mx16.
- Access times of 15/20 ns.
- Lower and upper byte selects to allow byte writes.
- Commercial & Industrial temperature grades.
- Multichip BGA - 192 (16x12) matrix 1mm Pitch.
- Eutectic 63/67 solder ball attach.
- Low Power Dissipation.

Operating	2.18 W (Max)
Standby (CMOS)	1W (Max)
- Completely Static Operation.

Package Details

192D - 192 Ball, 1mm pitch Multichip BGA
 Max. Dimensions (mm) - 19.50 x 15.00 x 1.40

Block Diagram



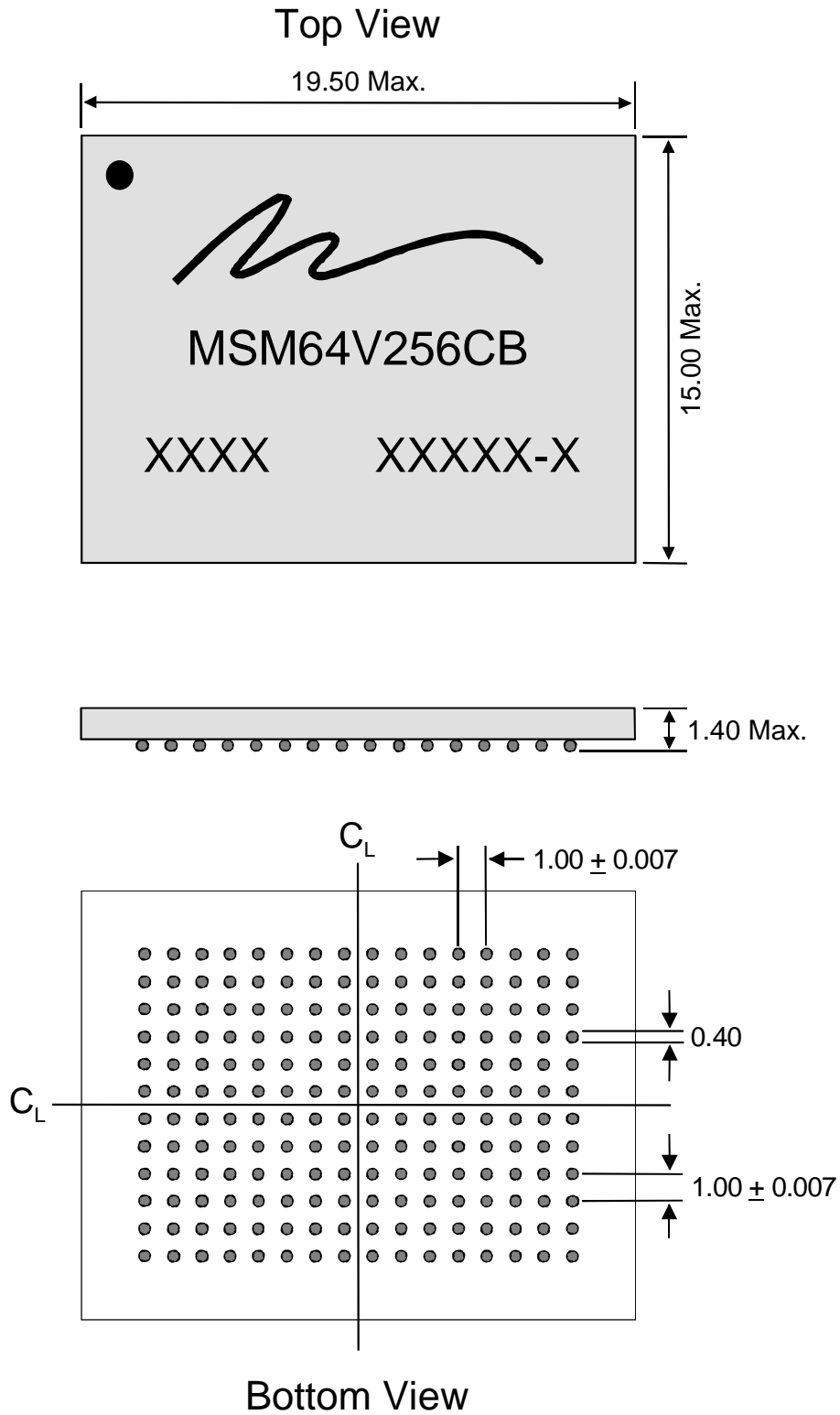
Pin Definition

To be announced.

Pin Functions

Description	Signal
Address Input	A0~A17
Data Input/Output	D0~D63
Chip Select	/CS1~4
Lower Byte Select	/LB1~4
Upper Byte Select	/UB1~4
Write Enable	/WE1~4
Output Enable	/OE
No Connect	NC
Power	V _{CC}
Ground	Gnd

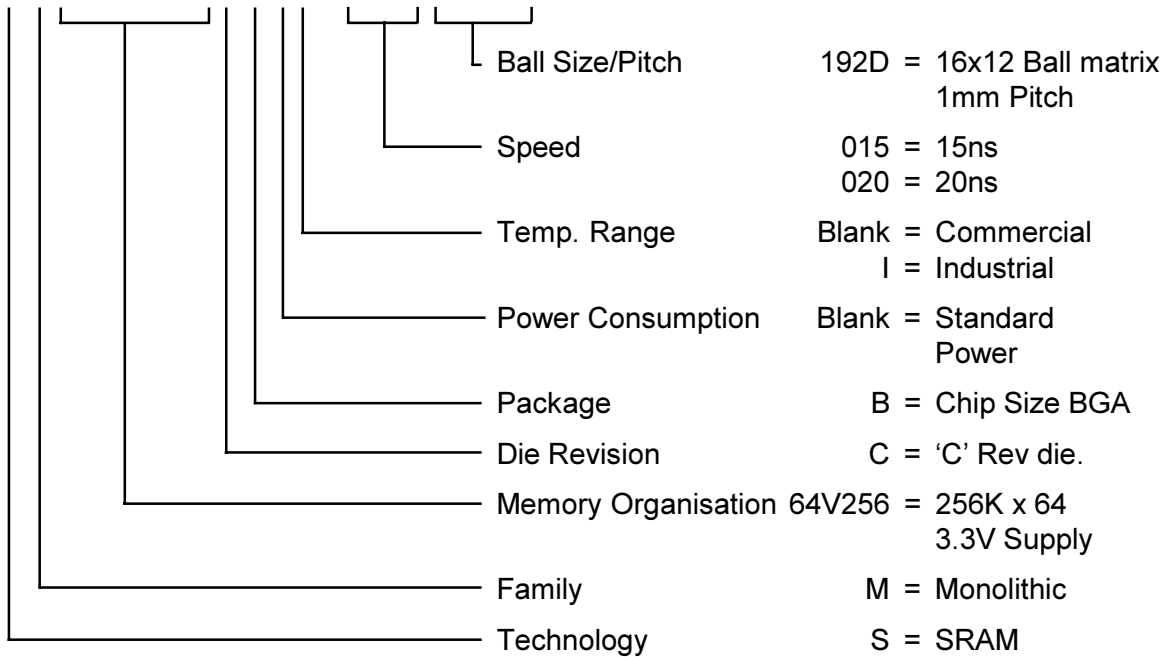
Chip Size BGA - 192 ball



Notes: All dimensions in millimetres.

Ordering Information

MSM64V256CBLI - 015/192D



Note :

Although this data is believed to be accurate the information contained herein is not intended to and does not create any warranty of merchantability or fitness for a particular purpose.

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Products are not authorised for use as critical components in life support devices without the express written approval of a company director.